

UÄur BÃ¼yÃ¼k

List of Publications by Year in descending order

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times ranked

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citing authors

#	ARTICLE	IF	CITATIONS
1	Variation of microindentation hardness with solidification and microstructure parameters in the Al based alloys. Applied Surface Science, 2008, 255, 3071-3078.	6.1	62
2	Dependency of the thermal and electrical conductivity on the temperature and composition of Cu in the Al based Al-Cu alloys. Experimental Thermal and Fluid Science, 2010, 34, 1507-1516.	2.7	62
3	Directional solidification of Al-Cu-Ag alloy. Applied Physics A: Materials Science and Processing, 2009, 95, 923-932.	2.3	59
4	Experimental investigation of the effect of solidification processing parameters on the rod spacings in the Sn-1.2wt.% Cu alloy. Journal of Alloys and Compounds, 2009, 486, 199-206.	5.5	44
5	The effects of microstructure and growth rate on microhardness, tensile strength, and electrical resistivity for directionally solidified Al-Ni-Fe alloys. Journal of Alloys and Compounds, 2016, 660, 23-31.	5.5	44
6	The effect of growth rate on microstructure and microindentation hardness in the In-Bi-Sn ternary alloy at low melting point. Journal of Alloys and Compounds, 2009, 470, 150-156.	5.5	43
7	The microstructure parameters and microhardness of directionally solidified Sn-Ag-Cu eutectic alloy. Journal of Alloys and Compounds, 2009, 485, 264-269.	5.5	43
8	Dependency of eutectic spacings and microhardness on the temperature gradient for directionally solidified Sn-Ag-Cu lead-free solder. Materials Chemistry and Physics, 2010, 119, 442-448.	4.0	36
9	Microstructural characterization of unidirectional solidified eutectic Al-Si-Ni alloy. Materials Characterization, 2011, 62, 844-851.	4.4	35
10	Determination of mechanical, electrical and thermal properties of the Sn-Bi-Zn ternary alloy. Journal of Non-Crystalline Solids, 2011, 357, 2876-2881.	3.1	33
11	Effect of silicon content on microstructure, mechanical and electrical properties of the directionally solidified Al-based quaternary alloys. Journal of Alloys and Compounds, 2017, 694, 471-479.	5.5	32
12	Solid-liquid interfacial energy of pyrene. Journal of Applied Physics, 2006, 100, 123505.	2.5	28
13	Measurement of solid-liquid interfacial energy in succinonitrile-pyrene eutectic system. Materials Letters, 2005, 59, 2953-2958.	2.6	27
14	Solid-liquid interfacial energy for solid succinonitrile in equilibrium with succinonitrile dichlorobenzene eutectic liquid. Thermochimica Acta, 2006, 445, 86-91.	2.7	25
15	Solid-liquid interfacial energy of dichlorobenzene. Journal of Physics Condensed Matter, 2007, 19, 116202.	1.8	25
16	Variations of microhardness with solidification parameters and electrical resistivity with temperature for Al-Cu-Ag eutectic alloy. Current Applied Physics, 2012, 12, 7-10.	2.4	25
17	Investigation of liquid composition effect on Gibbs-Thomson coefficient and solid-liquid interfacial energy in SCN based binary alloys. Materials Characterization, 2008, 59, 998-1006.	4.4	23
18	Measurement of solid-liquid interfacial energy in the pyrene succinonitrile monotectic system. Journal of Physics Condensed Matter, 2006, 18, 8403-8412.	1.8	22

#	ARTICLE	IF	CITATIONS
19	Determination of interfacial energies in the Al–Ag and Sn–Ag alloys by using Bridgman type solidification apparatus. <i>Journal of Alloys and Compounds</i> , 2009, 488, 138-143.	5.5	22
20	Dependence of Electrical Resistivity on Temperature and Sn Content in Pb-Sn Solders. <i>Journal of Electronic Materials</i> , 2011, 40, 195-200.	2.2	22
21	Novel experimental technique to observe equilibrated grain boundary groove shapes in opaque alloys. <i>Journal of Alloys and Compounds</i> , 2009, 476, 213-219.	5.5	21
22	Effect of solidification parameters on the microstructure of Sn-3.7Ag-0.9Zn solder. <i>Materials Characterization</i> , 2010, 61, 1260-1267.	4.4	21
23	Interfacial energy of solid In ₂ Bi intermetallic phase in equilibrium with In–Bi eutectic liquid at 72 Å°C equilibrating temperature. <i>Materials Characterization</i> , 2008, 59, 1101-1110.	4.4	20
24	Measurements of Microhardness and Thermal and Electrical Properties of the Binary Zn-0.7wt.%Cu Hypoperitectic Alloy. <i>Journal of Electronic Materials</i> , 2010, 39, 303-311.	2.2	17
25	Measurement of solid–liquid interfacial energy in the In–Bi eutectic alloy at low melting temperature. <i>Journal of Physics Condensed Matter</i> , 2007, 19, 506102.	1.8	16
26	Investigation of the effect of solidification processing parameters on the rod spacings and variation of microhardness with the rod spacing in the Sn–Cu hypereutectic alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2010, 21, 608-618.	2.2	15
27	Investigation of the effect of solidification processing parameters on microhardness and determination of thermo–physical properties in the Zn–Cu peritectic alloy. <i>Journal of Alloys and Compounds</i> , 2010, 491, 143-148.	5.5	15
28	Unidirectional solidification of Zn-rich Zn-Cu hypoperitectic alloy. <i>Journal of Materials Research</i> , 2009, 24, 3422-3431.	2.6	14
29	Investigation of microhardness and thermo-electrical properties in the Sn–Cu hypereutectic alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2010, 21, 468-474.	2.2	13
30	Interfacial energies of p-dichlorobenzene–succinonitrile alloy. <i>Thermochimica Acta</i> , 2007, 463, 44-52.	2.7	11
31	Containerless solidification of Ag–Al and Ag–Cu eutectic alloys in a drop tube. <i>Journal of Alloys and Compounds</i> , 2013, 575, 96-103.	5.5	11
32	Determination of solid–liquid interfacial energy for a solid Sn in equilibrium with a Sn–Ag–Zn eutectic liquid. <i>Current Applied Physics</i> , 2011, 11, 1060-1066.	2.4	9
33	The influence of the growth rate on the eutectic spacings, undercoolings and microhardness of directional solidified bismuth–lead eutectic alloy. <i>Current Applied Physics</i> , 2013, 13, 587-593.	2.4	9
34	Directional solidification of Zn-Al-Cu eutectic alloy by the vertical Bridgman method. <i>Journal of Mining and Metallurgy, Section B: Metallurgy</i> , 2015, 51, 67-72.	0.8	7
35	Effect of growth velocity on microstructure and mechanical properties of directionally solidified 7075 alloy. <i>International Journal of Cast Metals Research</i> , 2020, 33, 11-23.	1.0	7
36	Directionally Solidified Al–Cu–Si–Fe Quaternary Eutectic Alloys. <i>Physics of Metals and Metallography</i> , 2020, 121, 78-83.	1.0	6

#	ARTICLE	IF	CITATIONS
37	Investigation of directional solidified Al-Ti alloy. Journal of Non-Crystalline Solids, 2009, 355, 1231-1239.	3.1	5
38	Solidification Behavior of Ge-Al Eutectic Alloy in a Drop Tube. Transactions of the Indian Institute of Metals, 2016, 69, 961-970.	1.5	5
39	Effect of Heat Treatment on the Microstructures and Mechanical Properties of Al-4Cu-1.5Mg Alloy. International Journal of Metalcasting, 2022, 16, 1020-1033.	1.9	5
40	MEASUREMENTS OF SOLID-LIQUID INTERFACIAL ENERGIES IN THE ORGANIC MONOTECTIC ALLOYS. Surface Review and Letters, 2009, 16, 203-214.	1.1	3
41	Interfacial energies of carbon tetrabromide. Current Applied Physics, 2009, 9, 359-366.	2.4	3
42	Microstructural, mechanical, electrical, and thermal properties of the Bi-Sn-Ag ternary eutectic alloy. Journal Wuhan University of Technology, Materials Science Edition, 2017, 32, 147-154.	1.0	3
43	Investigation of the thermo-electrical properties of A707 alloys. Thermochimica Acta, 2019, 673, 177-184.	2.7	3
44	Characterization of Rapidly Solidified Nd-Al and Nd-Ag Eutectic Alloys in Drop Tube. Advanced Engineering Materials, 2015, 17, 359-365.	3.5	1
45	The Effect of Growth Rate on the Microstructure and Mechanical Properties of 7020 Alloys. Journal of Materials Engineering and Performance, 0, , 1.	2.5	1
46	Effect of Robotics Technology in Science Education on Scientific Creativity and Attitude Development. Journal of Turkish Science Education, 2020, 18, 54-72.	0.7	1
47	DETERMINATION OF ANISOTROPY OF CRYSTAL-MELT INTERFACIAL ENERGY FROM THE OBSERVED GRAIN BOUNDARY GROOVE SHAPES AT MULTIPLE ORIENTATIONS. Surface Review and Letters, 2009, 16, 579-588.	1.1	0
48	Subtle nuances in personality differences between gifted children as perceived by parents and teachers. Gifted Education International, 2021, 37, 305-320.	1.8	0
49	EFFECT OF CU CONTENT AND GROWTH VELOCITY ON THE MICROSTRUCTURE PROPERTIES OF THE DIRECTIONALLY SOLIDIFIED AL-MN-CU TERNARY ALLOYS. EJONS International Journal of Mathematic Engineering and Natural Sciences, 2021, 5, 756-764.	0.0	0